L Number	Hits	Search Text	DB	Time stamp
1	922	438/687.ccls.	USPAT	2004/09/23
•		400/00/100101	GO. A.	13:04
2	710	438/694.ccls.	USPAT	2004/09/23
				13:07
3	1597	438/692.ccls.	USPAT	2004/09/23
		·		13:08
4	606	438/669.ccls.	USPAT	2004/09/23
				13:08
5	250	438/658.ccls.	USPAT	2004/09/23
				13:09
6	260	438/659.ccls.	USPAT	2004/09/23
			2	13:10
7	197	438/645.ccls.	USPAT	2004/09/23
				13:10
8	122	438/707.ccls.	USPAT	2004/09/23
				13:11
9	758	438/710.ccls.	USPAT	2004/09/23
				13:11
10	658	438/720.ccls.	USPAT	2004/09/23
				13:14
11	31	west-jeffrey\$.in. barth-michael\$.in.	USPAT	2004/09/23
		zuhoski-steven\$.in.		13:14
12	11	west-jeffrey\$.in. barth-michael\$.in.	US-PGPUB	2004/09/23
		zuhoski-steven\$.in.		13:14
13	26	west-jeffrey\$.in. barth-michael\$.in.	EPO; JPO;	2004/09/23
		zuhoski-steven\$.in.	DERWENT;	13:14
	0		IBM_TDB	Α.
14	8497	(copper "cu") same (polish\$6 cmp)	USPAT	2004/09/23
				13:25
15	5430	((copper "cu") same (polish\$6 cmp)) and	USPAT	2004/09/23
4.0		(silane silicon)		13:24
16	3587	(((copper "cu") same (polish\$6 cmp)) and	USPAT	2004/09/23
		(silane silicon)) and ((silane silicon) same		13:16
47	4000	(copper "cu"))		
17	1968	((((copper "cu") same (polish\$6 cmp)) and	USPAT	2004/09/23
		(silane silicon)) and ((silane silicon) same		13:25
40	567	(copper "cu"))) and plasma	HODAT	2004/00/02
18	, 201	(((((copper "cu") same (polish\$6 cmp)) and	USPAT	2004/09/23
		(silane silicon)) and ((silane silicon) same		13:24
		(copper "cu"))) and plasma) and (((copper "cu") adj2 (polish\$6 cmp)) ((polish\$6 cmp)		
19	1326	adj2 (copper "cu")))	US-PGPUB	2004/00/22
		(((copper "cu") adj2 (polish\$6 cmp)) ((polish\$6 cmp) adj2 (copper "cu")))	US-FGFUB	2004/09/23 13:24
20	1086	((((copper "cu") adj2 (polish\$6 cmp))	US-PGPUB	2004/09/23
	1000	(((copper cu / au)z (ponshao cmp)) ((polish\$6 cmp) adj2 (copper "cu")))) and	00-70708	13:26
		(silane silicon)		15.25
22	533	(((((copper "cu") adj2 (polish\$6 cmp))	US-PGPUB	2004/09/23
		(((copper cu) adj2 (polish#6 chip)) ((polish#6 cmp) adj2 (copper "cu")))) and		13:25
	·	(silane silicon)) and plasma		

23	4434	(copper "cu") same (polish\$6 cmp)	EPO; JPO;	2004/09/23
			DERWENT;	13:25
		,	IBM_TDB	
24	483	((copper "cu") same (polish\$6 cmp)) and	EPO; JPO;	2004/09/23
		(silane silicon)	DERWENT;	13:26
			IBM_TDB	